2SK757

Silicon N-channel Power F-MOS FET

■ Features

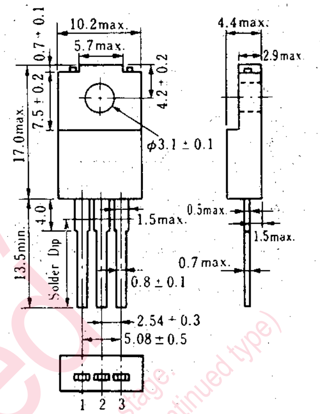
- Low ON resistance R_{DS} (on) : R_{DS} (on) = 0.22Ω (typ.)
- High switching rate : t_f = 60ns (typ.)
- No secondary breakdown

■ Application

- DC-DC converter
- No contact relay
- Solenoid drive
- Motor drive

■ Package Dimensions

Unit: mm



1 : Gate
2 : Drain
3 : Source

TO-220 full pack package (a type)

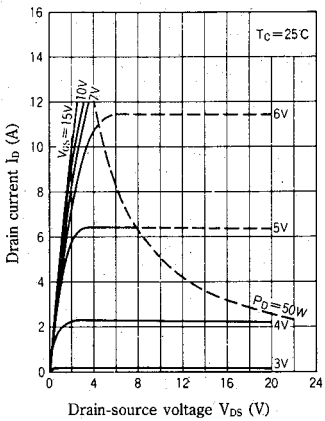
■ Absolute Maximum Ratings (Tc=25°C)

Item		Symbol	Value	Unit
Drain-source voltage		V_{DSS}	200	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC	I_D	10	A
	Peak-to-peak value	I_{DP}	20	
Power dissipation	Tc=25℃	P_D	50	W
	Ta=25℃		2.0	
Channel temperature		T_{ch}	150	℃
Storage temperature		T_{stg}	−55～+150	℃

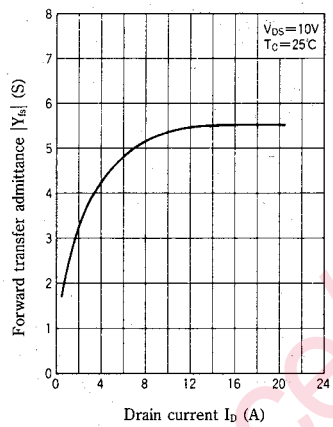
■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Drain current	I_{DSS}	V_{DS}=160V, V_{GS}=0			0.1	mA
Gate-source current	I_{GSS}	V_{GS}=±20V, V_{DS}=0			±1	μA
Drain-source voltage	V_{DSS}	I_D= 1 mA, V_{GS}=0	200			V
Gate threshold voltage	V_{th}	V_{DS}=10V, I_D=1mA	1		5	V
Drain-source ON resistance	R_{DS}(on)	V_{GS}=10V, I_D=5A		0.22	0.33	Ω
Forward transfer admittance	| Yfs |	V_{GS}=10V, I_D=5A	2.7	4.5		S
Input capacitance	C_{iss}	V_{DS}=10V, V_{GS}=0, f=1MHz		855		pF
Output capacitance	C_{oss}			330		pF
Reverse transfer capacitance	C_{rss}			150		pF
Turn-on time	t_{on}	V_{GS}=10V, I_D=5A V_{DD}=100V, R_L=20Ω		60		ns
Fall time	t_f			60		ns
Delay time	t_d(off)			150		ns

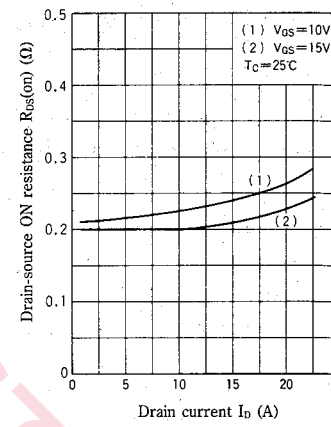
$I_D - V_{DS}$



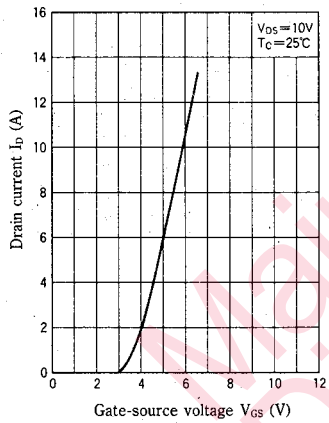
$|Y_{fs}| - I_D$



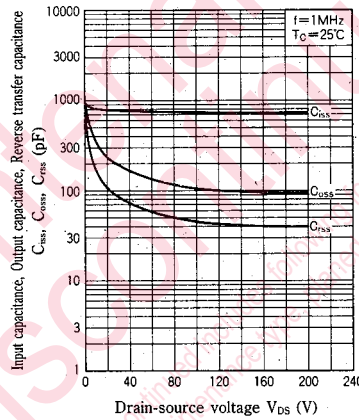
$R_{DS}(on) - I_D$



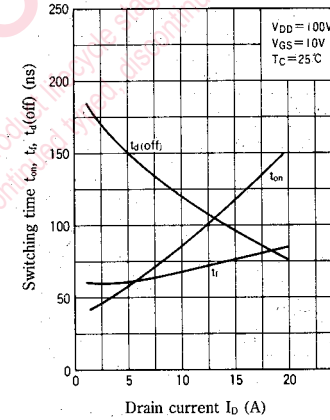
$I_D - V_{GS}$



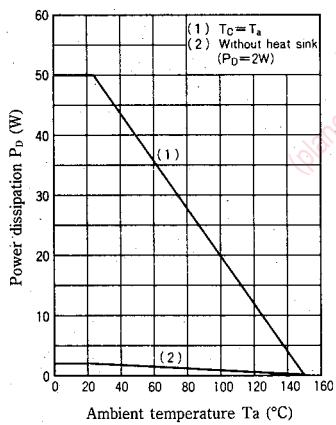
$C_{iss}, C_{oss}, C_{rss} - V_{DS}$



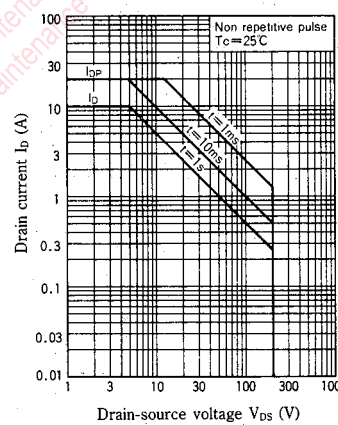
$t_{on}, t_f, t_d(off) - I_D$



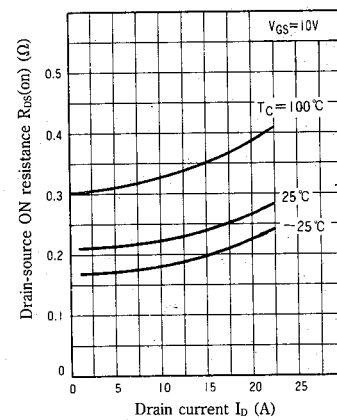
$P_D - Ta$



Safety operation area (ASO)



$R_{DS}(on) - I_D$



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